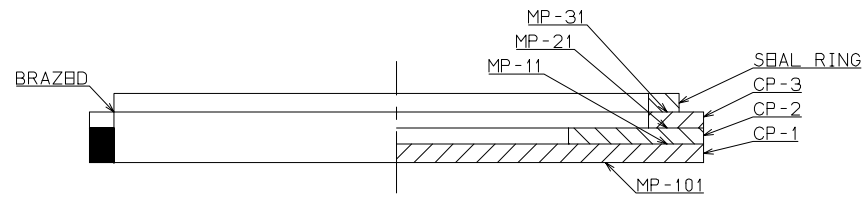


NOTES :

1. GENERAL TOLBRANCE : ±1% N.L.T. ±0.13.
2. ELBECTRIC Ni PLATING : 1.27~8.89 MICRON.(SOLDBR PAD)
ELBECTRIC Au PLATING : 1.00 MICRON MIN.(SOLDBR PAD)
3. * MARK TO BE MATERIAL DIMENSION.
4. CONNECTION : (A-4),(B-1),(2-3-S/R)
5. ■ PART TO BE SHOWN AS SIDB METALLIZED PATTERN.
6. SBALING MBTHOD OF THIS PRODUCT SHALL BE SBAM WELD.



TOLERANCE ±1% N.L.T.±0.13 ANGLES	REVISION					SBE ATTACHED EXCPPTIONS SHEBT.		TITLE	
	SCALE 25 : 1	DIMENSION mm	PROJECTION 3rd	CUSTOMER DWG NO.		REV.	5X3.2 L/T X'TAL		
MATERIAL 90%MIN.A1203 (NA-31B BLACK)	APPROVED Shigetomi Jan.17.03	CHECKED Yamahata Jan.17.03	ENGRG Ohba Jan.17.03	CHECKED Ano Jan.17.03	DESIGNED Sakima Jan.17.03	PART NO. S5032XTAL5		REV. 0	SHT/OF 1/5